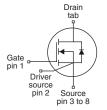
Vishay Siliconix

HALOGEN

**FREE** 

# **E Series Power MOSFET**





N-Channel MOSFET

PRODUCT SUMMARY				
$V_{DS}$ (V) at $T_J$ max.	650			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.043		
Q <sub>g</sub> max. (nC)	98			
Q <sub>gs</sub> (nC)	28			
Q <sub>gd</sub> (nC)	14			
Configuration	Single			

#### **FEATURES**

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

### **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SIHK045N60E-T1-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	600	W	
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	- I <sub>D</sub>	48	A	
	VGS at 10 V	T <sub>C</sub> = 100 °C		31		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	138	I	
Linear derating factor				2.22	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	286	mJ	
Maximum power dissipation			$P_{D}$	278	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope		T <sub>J</sub> = 125 °C	dv/dt	100	V/ns	
Reverse diode dv/dt <sup>d</sup>		av/at	17	V/IIS		

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 4.5 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	-	50 <sup>c</sup>	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.45	C/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static						•	
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.64	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
	I <sub>GSS</sub>	,	$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-source leakage		,	V <sub>GS</sub> = ± 30 V		-	± 1	μΑ
7		V <sub>DS</sub> =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 17 A	-	0.043	0.049	Ω
Forward transconductance a	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 35 A		-	22	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	4013	-	pF
Output capacitance	C <sub>oss</sub>	,	$V_{DS} = 100 \text{ V},$		148	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		-	6	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	117	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	744	-	
Total gate charge	Qg			-	65	98	
Gate-source charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$	$V_{GS} = 10 \text{ V}$ $I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$		28	-	nC
Gate-drain charge	Q <sub>gd</sub>	7			14	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 17 A,		-	35	70	
Rise time	t <sub>r</sub>			-	40	80	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		67	101	ns
Fall time	t <sub>f</sub>	1		-	14	28	
Gate input resistance	$R_g$	f = 1 MHz		0.4	0.8	1.6	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	48	
Pulsed diode forward current	I <sub>SM</sub>			-	-	148	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 17 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, $I_F = I_S = 17$ A, di/dt = 100 A/ $\mu$ s, $V_R = 25$ V		-	403	806	ns
Reverse recovery charge	Q <sub>rr</sub>			-	6.5	13	μC
Reverse recovery current	I <sub>RRM</sub>			_	26	_	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- c. When mounted on 1" x 1" FR4 board



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

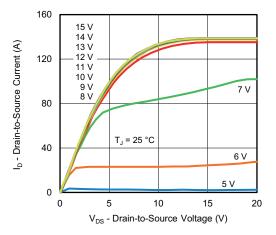


Fig. 1 - Typical Output Characteristics

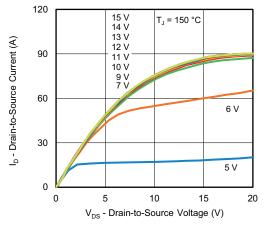


Fig. 2 - Typical Output Characteristics

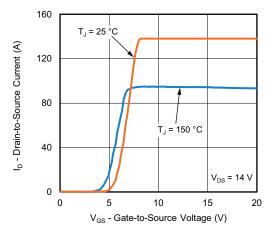


Fig. 3 - Typical Transfer Characteristics

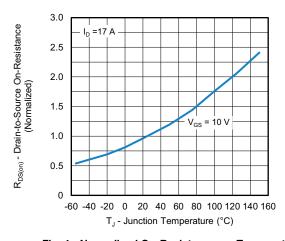


Fig. 4 - Normalized On-Resistance vs. Temperature

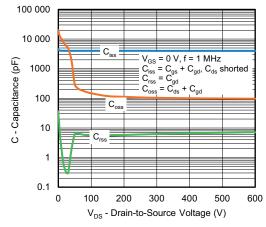


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

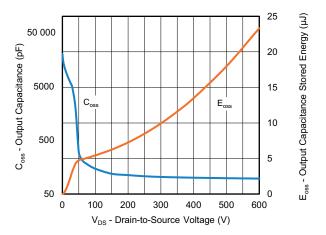


Fig. 6 - Coss and Eoss vs. VDS



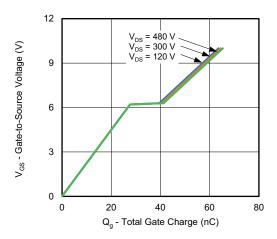


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

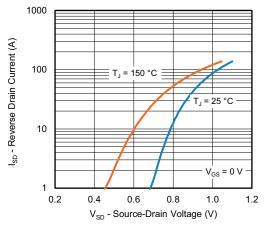


Fig. 8 - Typical Source-Drain Diode Forward Voltage

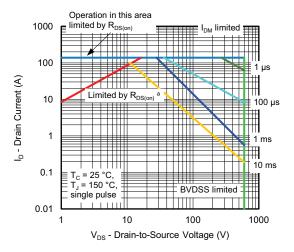


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS} > minimum \ V_{GS}$  at which  $R_{DS(on)}$  is specified

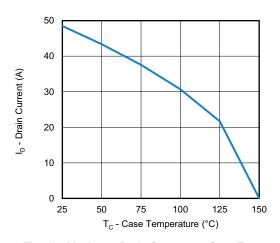


Fig. 10 - Maximum Drain Current vs. Case Temperature

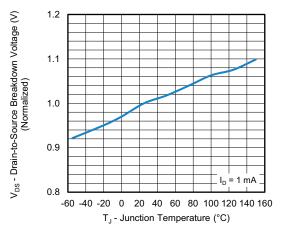


Fig. 11 - Temperature vs. Drain-to-Source Voltage



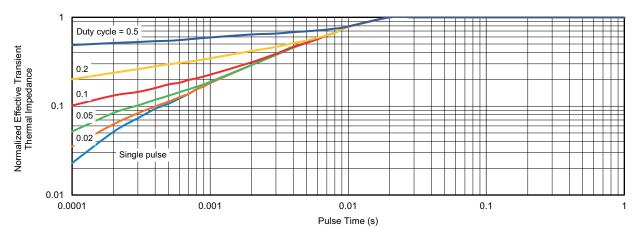


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

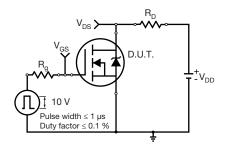


Fig. 13 - Switching Time Test Circuit

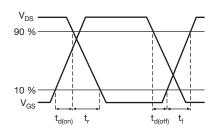


Fig. 14 - Switching Time Waveforms

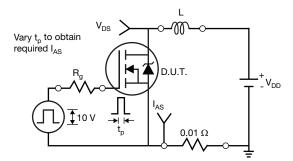


Fig. 15 - Unclamped Inductive Test Circuit

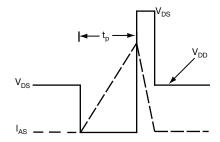


Fig. 16 - Unclamped Inductive Waveforms

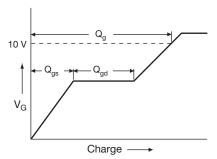


Fig. 17 - Basic Gate Charge Waveform

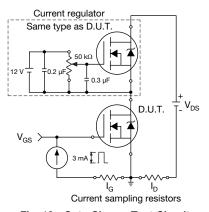
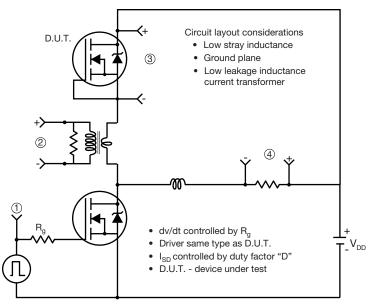


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dv/dt Test Circuit



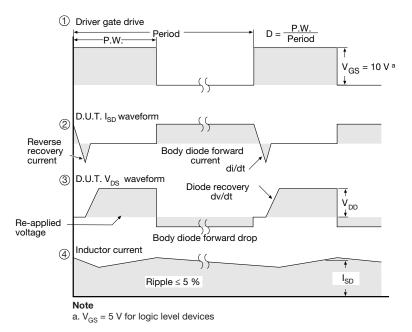
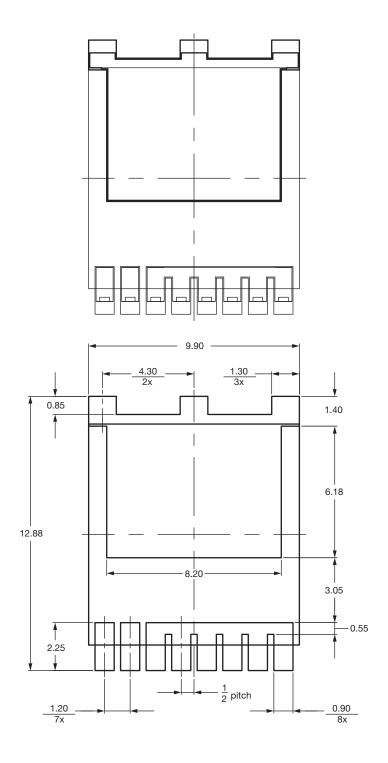


Fig. 19 - For N-Channel

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# Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



#### Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022

DWG: 3013



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